



ABSTRACT OF THE DISCLOSURE

61 An IC socket includes a socket body (1) for supporting lower end sections of bow-shaped contact pins (3), a floating member (2) provided with holes (2a) for guiding upper end sections of the contact pins (3), and a cover member (4) for pressing the floating member. Borders of the guide holes (2a) act as stoppers for the upper end sections of the contact pins (3) for regulating height of projection thereof from the floating member (2) and contact positions thereof in reference to solder ball terminals to prevent damage to the solder ball terminals of the IC package even if the solder balls are softened under a heat-resistance test or the like. In one embodiment, the IC socket can effectively perform wiping of the solder balls when it is used at an ordinary temperature. The cover member (4) may be used and formed with a surface (4b) for first engaging the IC package and another surface (4a) for subsequently engaging the top surface of the floating member (2). The lower end sections of the contact pins (3) may be fixed in the socket body (1) or may be movably supported.

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